



P-Channel 1.25-W, 1.8-V (G-S) MOSFET

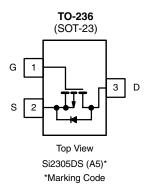
PRODUCT SUMMARY				
V _{DS} (V)	r _{DS(on)} (Ω)	I _D (A)		
	0.052 at $V_{GS} = -4.5 \text{ V}$	± 3.5		
- 8	0.071 at V _{GS} = - 2.5 V	± 3		
	0.108 at V _{GS} = - 1.8 V	± 2		

FEATURES

• TrenchFET® Power MOSFETs: 1.8 V Rated



RoHS*



Ordering Information: Si2305DS-T1

Si2305DS-T1-E3 (Lead (Pb)-free)

ABSOLUTE MAXIMUM RATINGS $T_A = 25$ °C, unless otherwise noted					
Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		V _{DS}	- 8	V	
Gate-Source Voltage		V _{GS} ± 8			
Continuous Drain Current (T _{.1} = 150 °C)	T _A = 25 °C	I _D	± 3.5		
Continuous Diain Curient (1) = 130 C)	T _A = 70 °C		± 2.8		
Pulsed Drain Current		I _{DM} ± 12 I _S - 1.6		Α	
Continuous Source Current (Diode Conduction) ^{a, b}					
Mariana Barra Biratina in Alb	T _A = 25 °C	P _D	1.25	W	
Maximum Power Dissipation ^{a, b}	T _A = 70 °C	- FD	0.8] **	
Operating Junction and Storage Temperature Range		T _J , T _{stg}	- 55 to 150	°C	

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Typical	Maximum	Unit
Manipana Ingation to Ambienti	t ≤ 5 sec	R _{thJA}		100	°C/W
Maximum Junction-to-Ambient ^a	Steady State	' 'thJA	130		

Notes:

a. Surface Mounted on FR4 Board.

 $b.\ t \leq 5\ sec.$

^{*} Pb containing terminations are not RoHS compliant, exemptions may apply.

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Damana dam	Cumbal	Test Conditions	Limits			I I m if	
Parameter	Symbol	lest Conditions	Min	Тур	Max	Unit	
Static							
Drain-Source Breakdown Voltage	V _{(BR)DSS}	$V_{GS} = 0 \text{ V}, I_D = -10 \mu\text{A}$	- 8	- 8		V	
Gate-Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = -250 \mu A$	- 0.45		- 0.8	v	
Gate-Body Leakage	I_{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 8 \text{ V}$			± 100	nA	
Zero Gate Voltage Drain Current		V _{DS} = - 8 V, V _{GS} = 0 V			- 1	μΑ	
	I _{DSS}	$V_{DS} = -8 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 ^{\circ}\text{C}$			- 10		
On-State Drain Current ^a	1	$V_{DS} \le -5 \text{ V}, V_{GS} = -4.5 \text{ V}$	- 6			Λ	
	I _{D(on)}	$V_{DS} \le -5 \text{ V}, V_{GS} = -2.5 \text{ V}$	- 3			Α	
Drain-Source On-Resistance ^a		V _{GS} = - 4.5 V, I _D = - 3.5 A		0.044	0.052		
	r _{DS(on)}	V _{GS} = - 2.5 V, I _D = - 3 A		0.060	0.071	Ω	
		V _{GS} = - 1.8 V, I _D = - 2 A		0.087	0.108		
Forward Transconductance ^a	9 _{fs}	V _{DS} = - 5 V, I _D = - 3.5 A		8.5		S	
Diode Forward Voltage	V_{SD}	I _S = - 1.6 A, V _{GS} = 0 V			- 1.2	V	
Dynamic ^b							
Total Gate Charge	Q_g			10	15		
Gate-Source Charge	Q _{gs}	V_{DS} = - 4 V, V_{GS} = - 4.5 V, I_D \cong - 3.5 A		2		nC	
Gate-Drain Charge	Q_{gd}			2			
Input Capacitance	C _{iss}			1245			
Output Capacitance	C _{oss}	$V_{DS} = -4 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		375		pF	
Reverse Transfer Capacitance	C _{rss}			210			
Switching ^b							
Turn On Time	t _{d(on)}			13	20		
Turn-On Time	t _r	V_{DD} = - 4 V, R_L = 4 Ω		25	40		
Turn-Off Time	t _{d(off)}	$I_D\cong$ - 1.0 A, V_{GEN} = - 4.5 V, R_G = 6 Ω		55	80	ns	
ium-on time	t _f			19	35		

Notes:

- a. For DESIGN AID ONLY, not subject to production testing.
- b. Pulse test: PW \leq 300 $\mu s,$ duty cycle \leq 2 %.
- c. Switching time is essentially independent of operating temperature.

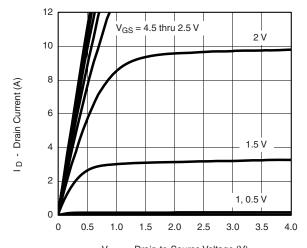
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



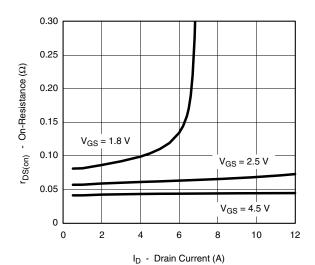




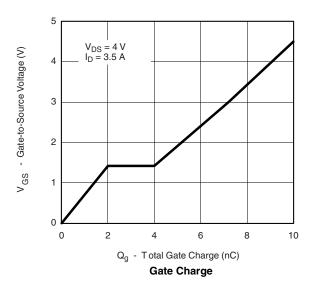
TYPICAL CHARACTERISTICS 25 °C, unless noted



V_{DS} - Drain-to-Source Voltage (V) **Output Characteristics**

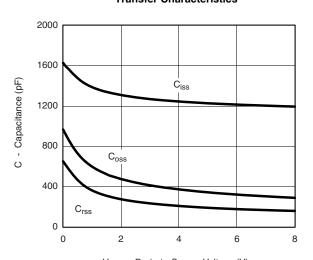


On-Resistance vs. Drain Current



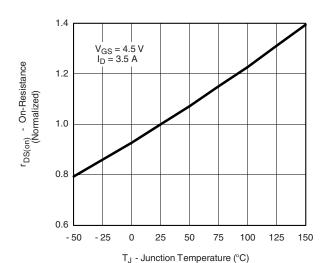
12 $T_C = -55$ °C 10 25 °C 8 I_D - Drain Current (A) 125 °C 6 4 2 0 0 0.5 1.0 2.0 2.5

V_{GS} - Gate-to-Source Voltage (V) **Transfer Characteristics**



V_{DS} - Drain-to-Source Voltage (V)



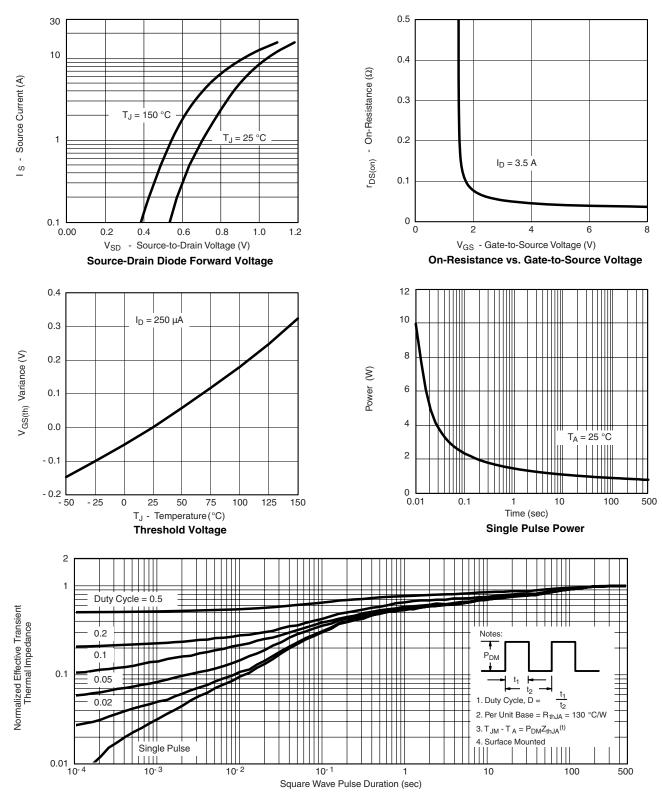


On-Resistance vs. Junction Temperature

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TYPICAL CHARACTERISTICS 25 °C, unless noted



Normalized Thermal Transient Impedance, Junction-to-Ambient

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